

DDI(Display Driver IC) Code Information (1/2)

Last Updated : April 2008

S 6 X X X X X X X X - X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15

1. System LSI (S)

2. Large Classification : DDI (6)

3. Small Classification

A : STN (Character)	B : STN (Graphic)
C : TFT (Large)	D : TFT (Mobile)
E : OELD	F : TFT (Midsmall)
K : OELD (Large)	P : PDI (DUAL)
T : TCON	V : Process Vehicle

4~7.

Serial No.

8. Version

A~Z

*1st Version → X

9~10. Mask Option

- STN (Character)

00~99 : Font

- STN (Graphic)

Mask Option

- TFT Device

Mask Option

11. " - "

12~14. Package Type

- In Case of PKG

(12) Package Type

A : SDIP	B : BUMP BIZ
C : CHIP BIZ	E : LQFP
J : ELP	K : TR
N : COB	Q : QFP
S : SOP	T : TQFP
W : WAFER	X : ETQFP
Y : FBGA	

(13) Reserved

- PKG Option

0 : none

1 : Special Handling 1

3 : Special Handling 3

5 : Special Handling 5

A : Test Condition 1

C : Customer Option 2

E : Customer Option 4

G : Customer Option 6

J : Customer Option 8

L : Customer Option 10

N : Customer Option 12

Q : Customer Option 14

S : Customer Option 16

U : Customer Option 18

W : Customer Option 20

2 : Special Handling 2

4 : Special Handling 4

6 : Special Handling 6

B : Customer Option 1

D : Customer Option 3

F : Customer Option 5

H : Customer Option 7

K : Customer Option 9

M : Customer Option 11

P : Customer Option 13

R : Customer Option 15

T : Customer Option 17

V : Customer Option 19

- WAFER

0 : BUMP

1 : NO BUMP

(14) Packing

- In Case of TAB / COF

(12)(13) Film Type

00~49 → TAB

50~99 → COF

(14) Revision

1st Version → X

DDI(Display Driver IC) Code Information (2/2)

Last Updated : April 2008

<u>S</u>	<u>6</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	-	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15

15. Back Lap

- 0 : No Grinding
- 1 : 250 ± 10um
- 3 : 140 ± 10um
- 5 : 200 ± 10um
- 6 : 220 ± 10um
- 7 : 170 ± 10um (Polishing / Grinding)
- 8 : 300 ± 10um (CHIP BIZ)
- 9 : 280 ± 10um
- A : 300 ± 10um
- C : 300 ± 10um (Wafer)
- D : 350 ± 10um
- G : 375 ± 10um (CHIP BIZ)
- J : 425 ± 10um
- K : 400 ± 10um
- L : 450 ± 10um
- M : 470 ± 10um (Wafer)
- N : 470 ± 10um
- R : 350 ± 10um (Wafer)
- U : 610 ± 10um
- V : 500 ± 10um (CHIP BIZ)
- W : 425 ± 10um (Wafer)
- X : 425 ± 10um (CHIP BIZ)
- Y : 470 ± 10um (CHIP BIZ)
- Z : No Grinding (CHIP / Wafer)